

FGZ40N120WE

Discrete IGBT (High-Speed W series) 1200V / 40A

Features

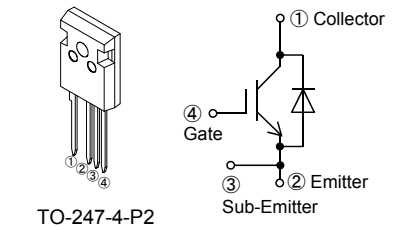
- Low power loss
- Low switching surge and noise
- High reliability, high ruggedness (RBSOA, SCSOA etc.)

Applications

- Uninterruptible power supply
- PV Power conditioner
- Inverter welding machine



Equivalent circuit



Maximum Ratings and Characteristics

Absolute Maximum Ratings at $T_{vj}=25^{\circ}\text{C}$ (unless otherwise specified)

Items	Symbol	Characteristics	Unit	Remarks
Collector-Emitter Voltage	V_{CES}	1200	V	
Gate-Emitter Voltage	V_{GES}	± 20	V	
Transient Gate-Emitter Voltage		± 30	V	$T_r < 1\mu\text{s}$
DC Collector Current	$I_{C@25}$	65	A	$T_c=25^{\circ}\text{C}$
	$I_{C@100}$	40	A	$T_c=100^{\circ}\text{C}$
Pulsed Collector Current	I_{CP}	160	A	Note *1
Turn-Off Safe Operating Area	-	160	A	$V_{CE} \leq 650\text{V}, T_{vj} \leq 175^{\circ}\text{C}$
Diode Forward Current	$I_{F@25}$	60	A	
	$I_{F@100}$	40	A	
Diode Pulsed Current	I_{FP}	160	A	Note *1
IGBT Max. Power Dissipation	P_{tot_IGBT}	430	W	$T_c=25^{\circ}\text{C}$
FWD Max. Power Dissipation	P_{tot_FWD}	190	W	$T_c=25^{\circ}\text{C}$
Operating Junction Temperature	T_{vj}	-40 ~ +175	$^{\circ}\text{C}$	
Storage Temperature	T_{stg}	-55 ~ +175	$^{\circ}\text{C}$	

Note *1 : Pulse width limited by T_{vjmax} .

Electrical characteristics at $T_{vj}=25^{\circ}\text{C}$ (unless otherwise specified) Static Characteristics

Description	Symbol	Conditions	min.	typ.	max.	Unit	
Zero Gate Voltage Collector Current	I_{CES}	$V_{CE} = 1200\text{V}, V_{GE} = 0\text{V}$	$T_{vj}=25^{\circ}\text{C}$	-	-	250	μA
			$T_{vj}=175^{\circ}\text{C}$	-	-	2	mA
Gate-Emitter Leakage Current	I_{GES}	$V_{CE} = 0\text{V}, V_{GE} = \pm 20\text{V}$	-	-	200	nA	
Gate-Emitter Threshold Voltage	$V_{GE(th)}$	$V_{CE} = 20\text{V}, I_C = 40\text{mA}$	5.0	6.0	7.0	V	
Collector-Emitter Saturation Voltage	$V_{CE(sat)}$	$V_{GE} = 15\text{V}, I_C = 40\text{A}$	$T_{vj}=25^{\circ}\text{C}$	-	2.0	2.6	V
			$T_{vj}=175^{\circ}\text{C}$	-	2.6	-	
Input Capacitance	C_{ies}	$V_{CE}=25\text{V}$	-	2500	-	pF	
Output Capacitance	C_{oes}	$V_{GE}=0\text{V}$	-	110	-		
Reverse Transfer Capacitance	C_{res}	$f=1\text{MHz}$	-	34	-		
Gate Charge	Q_G	$V_{CC} = 600\text{V}$ $I_C = 40\text{A}$ $V_{GE} = 15\text{V}$	-	120	-	nC	
Turn-On Delay Time	$t_{d(on)}$	$T_{vj} = 25^{\circ}\text{C}, V_{CC} = 600\text{V}$ $I_C = 40\text{A}, V_{GE} = 15\text{V}$ $R_G = 10\Omega$	-	30	-	ns	
Rise Time	t_r		-	16	-		
Turn-Off Delay Time	$t_{d(off)}$		-	150	-		
Fall Time	t_f		-	50	-		
Turn-On Energy	E_{on}	Energy loss include "tail" and FWD reverse recovery.	-	1.1	-	mJ	
Turn-Off Energy	E_{off}		-	1.4	-		
Turn-On Delay Time	$t_{d(on)}$		-	30	-		
Rise Time	t_r		-	20	-		
Turn-Off Delay Time	$t_{d(off)}$	$T_{vj} = 175^{\circ}\text{C}, V_{CC} = 600\text{V}$ $I_C = 40\text{A}, V_{GE} = 15\text{V}$ $R_G = 10\Omega$	-	190	-	ns	
Fall Time	t_f		-	104	-		
Turn-On Energy	E_{on}		-	2.5	-		
Turn-Off Energy	E_{off}		-	2.2	-		
Forward Voltage Drop	V_F	$I_F=40\text{A}$	$T_{vj}=25^{\circ}\text{C}$	-	2.40	3.36	V
			$T_{vj}=175^{\circ}\text{C}$	-	2.10	-	V
Diode Reverse Recovery Time	t_{rr}	$V_{CC}=600\text{V}, I_F = 40\text{A}$	-	0.45	-	μs	
Diode Reverse Recovery Charge	Q_{rr}	$-di/dt=600\text{A}/\mu\text{s}, T_{vj}=25^{\circ}\text{C}$	-	2.20	-	μC	
Diode Reverse Recovery Time	t_{rr}	$V_{CC}=600\text{V}, I_F=40\text{A}$	-	0.85	-	μs	
Diode Reverse Recovery Charge	Q_{rr}	$-di/dt=600\text{A}/\mu\text{s}, T_{vj}=175^{\circ}\text{C}$	-	7.10	-	μC	

● Thermal Resistance

Description	Symbol	min.	typ.	max.	Unit
Thermal Resistance, Junction-Ambient	$R_{th(j-a)}$	-	-	50	°C/W
Thermal Resistance, IGBT Junction to Case	$R_{th(j-c)}_{IGBT}$	-	-	0.347	°C/W
Thermal Resistance, FWD Junction to Case	$R_{th(j-c)}_{FWD}$	-	-	0.781	°C/W

■ Characteristics (Representative)

Figure 4. DC Collector Current vs T_c
 $V_{GE} \geq +15V, T_{vj} \leq 175^\circ C$

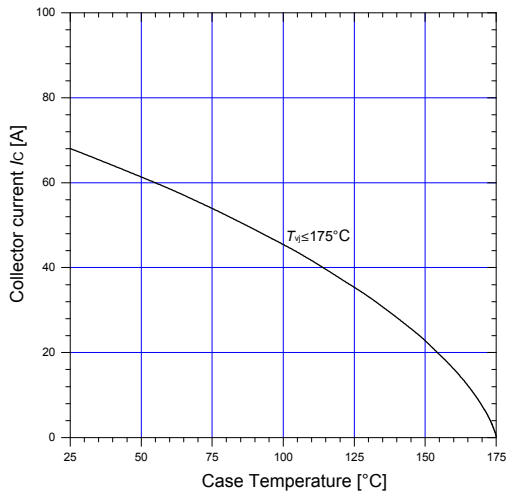


Figure 5. Collector Current vs. switching frequency
 $V_{GE}=15V, T_{vj} \leq 150^\circ C, V_{cc}=600V, R_G=10\Omega$
 Duty=0.5, $T_c=100^\circ C$

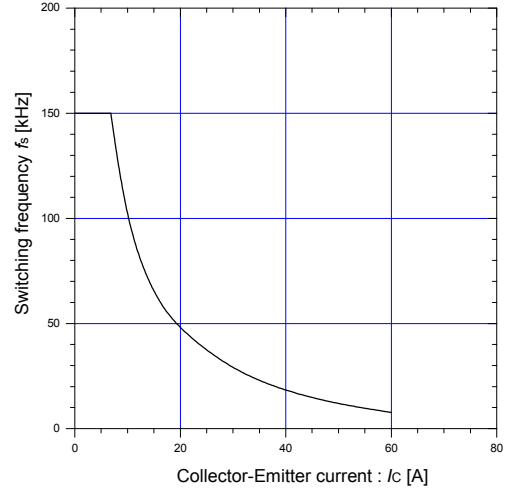


Figure 6. Typical output characteristics
 $T_{vj}=25^\circ C$

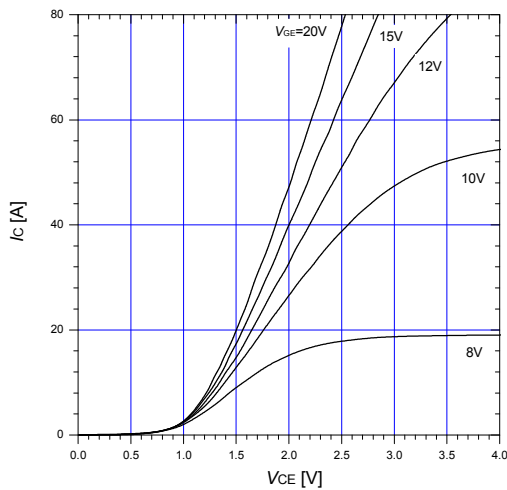


Figure 7. Typical output characteristics
 $T_{vj}=175^\circ C$

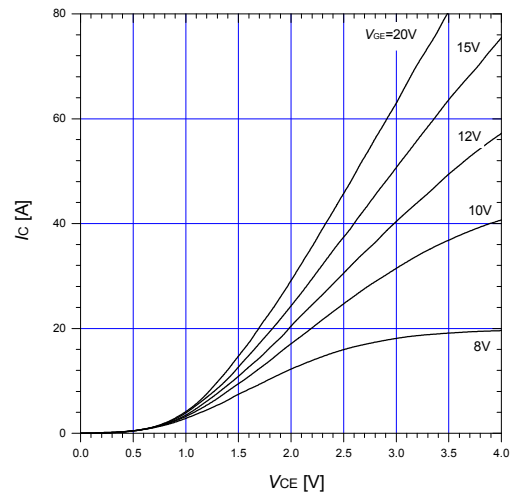


Figure 8. Typical transfer characteristics
 $V_{ce}=10V$

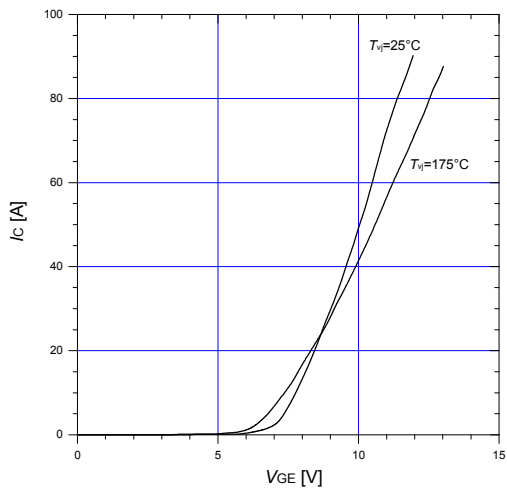


Figure 9. Gate threshold voltage
 $I_c=40mA, V_{ce}=20V$

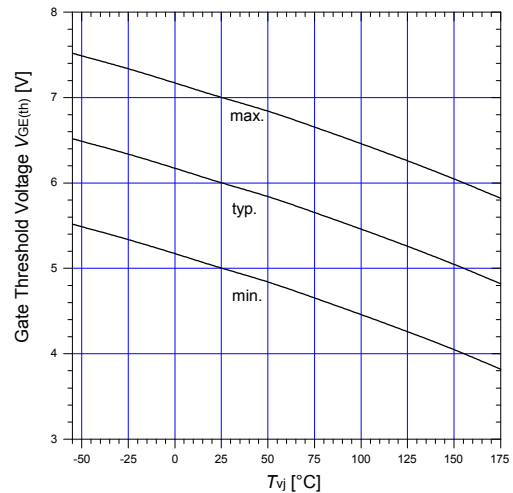


Figure 10. Typical capacitance

$V_{GE} = 0\text{ V}$, $f = 1\text{ MHz}$

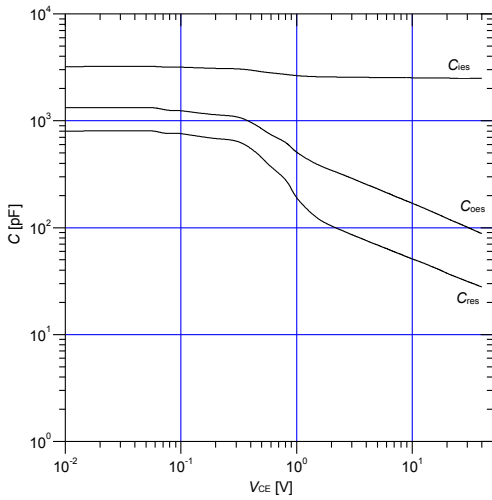


Figure 11. Typical gate charge

$I_C = 40\text{ A}$, $V_{CC} = 600\text{ V}$, $T_{vj} = 25^\circ\text{C}$

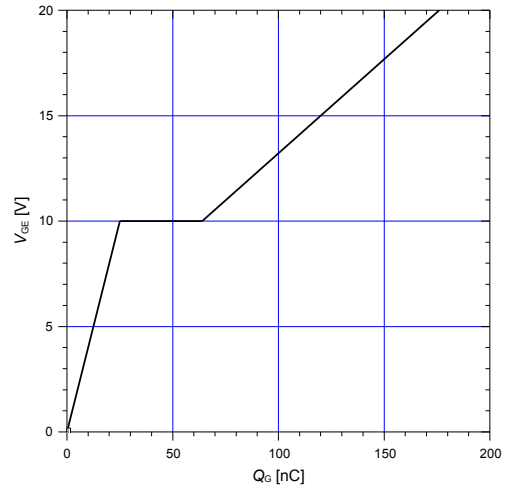


Figure 12. Typical switching times vs. I_C

$V_{CC} = 600\text{ V}$, $V_{GE} = 15\text{ V}$, $R_G = 10\ \Omega$, $T_j = 175^\circ\text{C}$

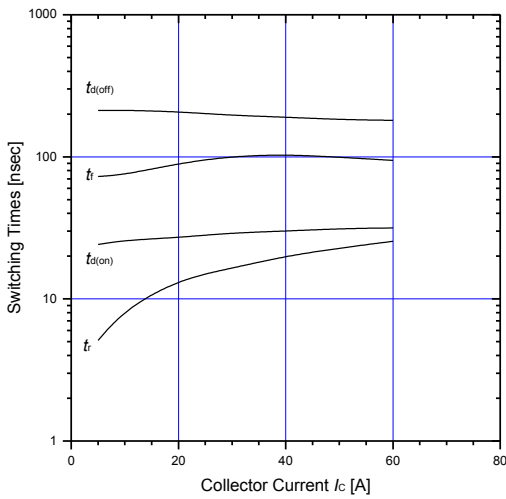


Figure 13. Typical switching times vs. R_G

$V_{CC} = 600\text{ V}$, $V_{GE} = 15\text{ V}$, $I_C = 40\text{ A}$, $T_j = 175^\circ\text{C}$

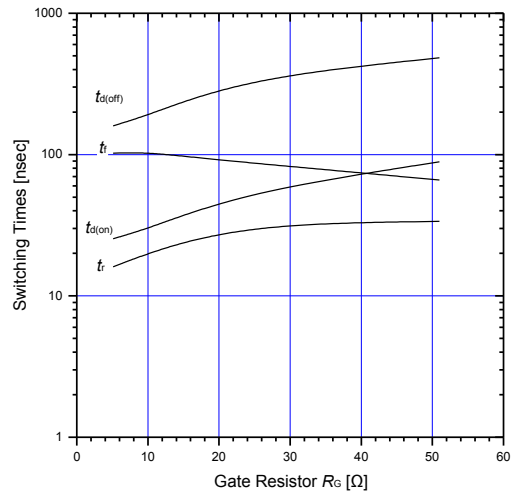


Figure 14. Typical switching losses vs. I_C

$V_{CC} = 600\text{ V}$, $V_{GE} = 15\text{ V}$, $R_G = 10\ \Omega$, $T_j = 175^\circ\text{C}$

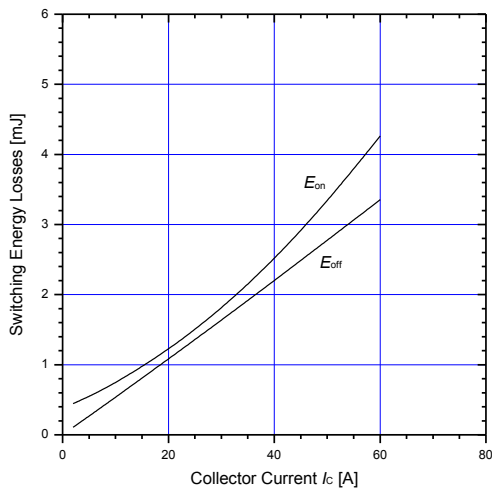


Figure 15. Typical switching losses vs. R_G

$V_{CC} = 600\text{ V}$, $V_{GE} = 15\text{ V}$, $I_C = 40\text{ A}$, $T_j = 175^\circ\text{C}$

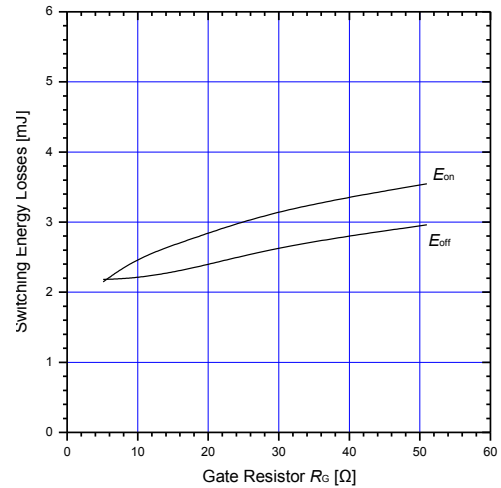


Figure 16. Typical forward characteristics of FWD

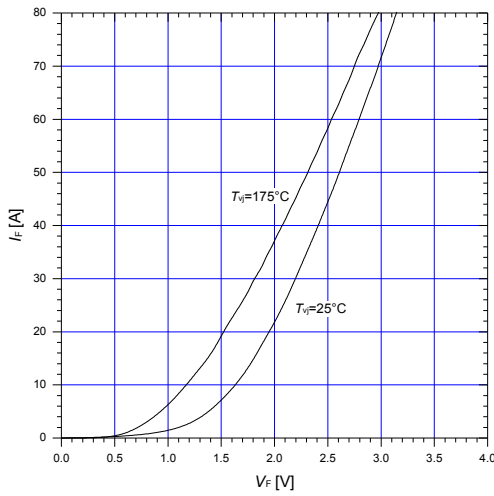


Figure 17.

Typical reverse recovery characteristics vs. I_F
 $V_{CC} = 600\text{ V}$, $V_{GE} = 15\text{ V}$, $R_G = 10\ \Omega$, $T_{vj} = 175^\circ\text{C}$

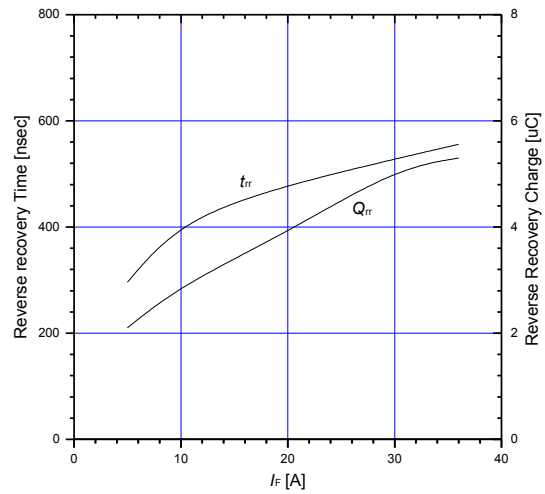


Figure 18. Typical reverse recovery loss vs. I_F

$V_{CC} = 600\text{ V}$, $V_{GE} = 15\text{ V}$, $R_G = 10\ \Omega$, $T_{vj} = 175^\circ\text{C}$

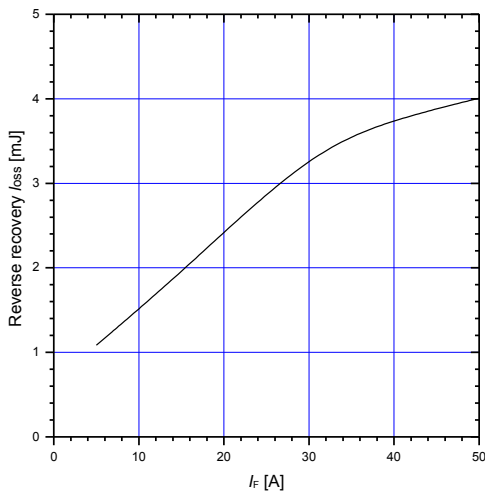


Figure 19. Reverse biased safe operating area

$V_{GE} = 15\text{ V} / 0\text{ V}$, $R_G = 10\ \Omega$, $T_{vj} \leq 175^\circ\text{C}$

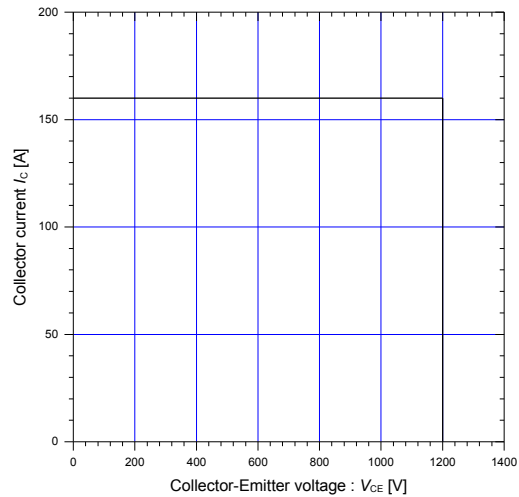


Figure 20. Transient Thermal Impedance of IGBT

$D = 0$

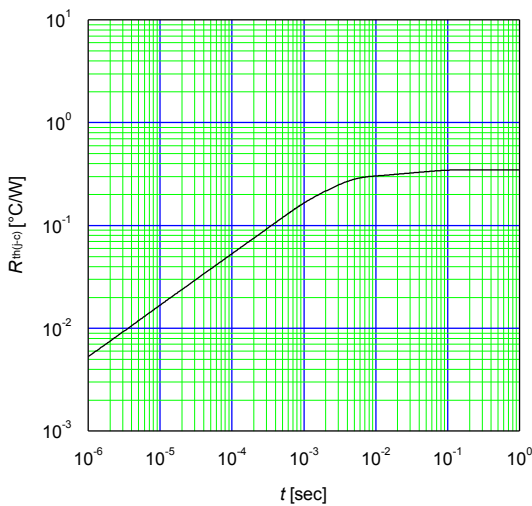
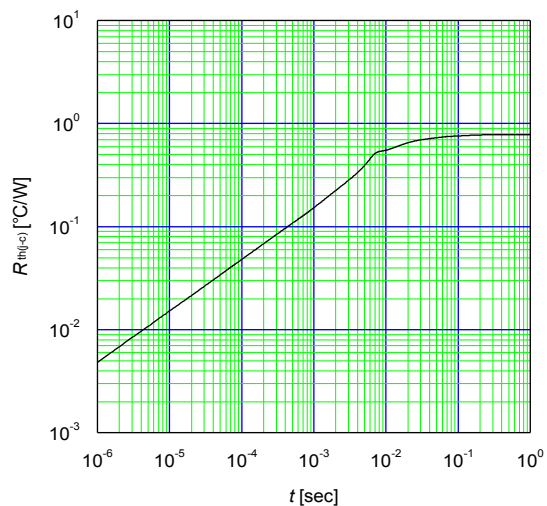


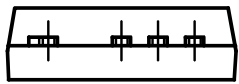
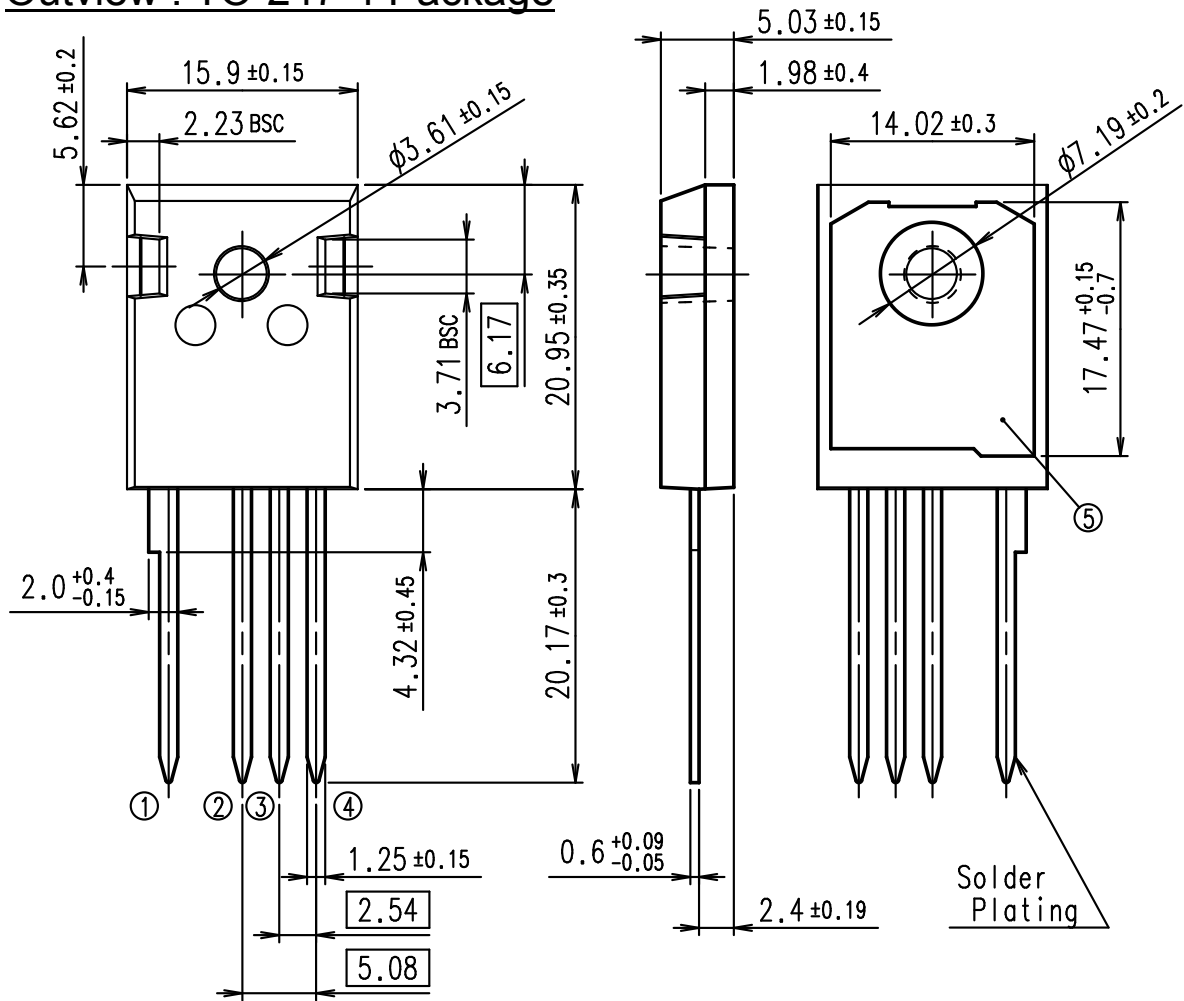
Figure 21. Transient Thermal Impedance of FWD

$D = 0$



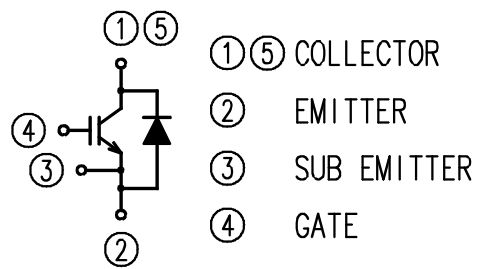
■ Outline Drawings, mm

Outview : TO-247-4 Package



DIMENSIONS ARE IN MILLIMETERS.

CONNECTION



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